ABSTRACT

[0303]

The present invention provides a laminate having a two-layer or three-layer structure including a non-thermoplastic polyimide film and a thermoplastic polyimide layer provided on one or both of the surfaces thereof, the surface of the thermoplastic polyimide layer being surface-treated; a laminate including a polymer film and a layer provided on one or both of the surfaces thereof, the layer including a polyimide resin composition comprising a polyimide resin with a specified structure and a thermosetting component; and a resin film and a laminate including the same which provided one, at least, of surface having a Ra1 value of arithmetic mean roughness of 0.05 μm to 1 μm measured with a cutoff value of 0.002 mm, and a Ra1/Ra2 ratio of 0.4 to 1, Ra2 being a value measured with a cutoff value of 0.1 mm. These laminates can provide a printed circuit board with excellent adhesiveness, on which a micro-wiring circuit can be formed.